

Features

- -100V/-18A,
 $R_{DS(ON)} = 85m\Omega(Typ.)@V_{GS}=-10V$
 $R_{DS(ON)} = 93m\Omega(Typ.)@V_{GS}=-4.5V$
- Excellent $Q_G \times R_{DS(on)}$ product(FOM)
- SGT Technology
- High Ruggedness
- 100% Avalanche Tested

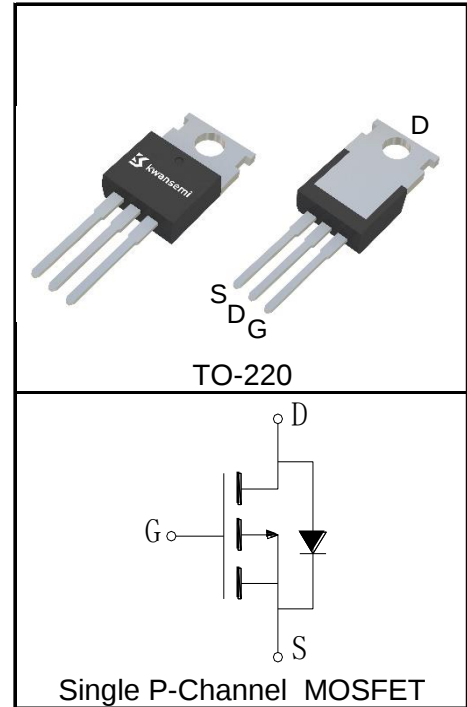
Applications

- Power Switching Appliaction
- Load Switching



Halogen-Free

Pin Description



Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (T _C =25°C Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage		-100	V
V _{GSS}	Gate-Source Voltage		±20	
T _{Jmax}	Maximum Junction Temperature		175	°C
T _J ,T _{STG}	Operating and Storage Temperature Range		-55 to 175	°C
I _S	Diode Continuous Forward Current	T _C =25°C	-18	A
Mounted on Large Heat Sink				
I _{DP} ^①	Pulse Drain Current	T _C =25°C	-72	A
I _D ^②	Continuous Drain Current(V _{GS} =-10V)	T _C =25°C	-18	A
		T _C =100°C	-12	
P _D	Maximum Power Dissipation	T _C =25°C	75	W
		T _C =100°C	37	
R _{θJC}	Thermal Resistance-Junction to Case		2	°C/W
R _{θJA} ^③	Thermal Resistance-Junction to Ambient		62.5	°C/W
Drain-Source Avalanche Ratings				
E _{AS} ^④	Avalanche Energy, Single Pulsed		132	mJ

Electrical Characteristics ($T_C=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	Rating			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-100			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-100V, V _{GS} =0V			-1	μA
		T _J =125°C			-30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250μA	-1.1	-1.9	-2.3	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
R _{DS(ON)} ⑤	Drain-Source On-state Resistance	V _{GS} =-10V, I _{DS} =-10A		85	100	mΩ
		V _{GS} =-4.5V, I _{DS} =-5A		93	120	mΩ
Diode Characteristics						
V _{SD} ⑤	Diode Forward Voltage	I _{SD} =-10A, V _{GS} =0V		-0.89	-1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =-10A, dI _{SD} /dt=-100A/μs		26		ns
Q _{rr}	Reverse Recovery Charge			83		nC
Dynamic Characteristics ⑥						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		11		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-50V, Frequency=1.0MHz		1130		pF
C _{oss}	Output Capacitance			110		
C _{rss}	Reverse Transfer Capacitance			7		
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-50V, I _{DS} =-10A, V _{GEN} =-10V, R _G =3Ω		13		ns
t _r	Turn-on Rise Time			24		
t _{d(OFF)}	Turn-off Delay Time			77		
t _f	Turn-off Fall Time			31		
Gate Charge Characteristics ⑥						
Q _g	Total Gate Charge	V _{DS} =-50V, V _{GS} =-10V, I _{DS} =-10A		31		nC
Q _{gs}	Gate-Source Charge			5.9		
Q _{gd}	Gate-Drain Charge			6.4		

- Notes:
- ① Pulse width limited by safe operating area.
 - ② Calculated continuous current based on maximum allowable junction temperature.
 - ③ When mounted on 1 inch square copper board, $t \leq 10\text{sec}$. The value in any given application depends on the user's specific board design.
 - ④ Limited by T_{Jmax} , Starting $T_J = 25^{\circ}\text{C}$, $I_{ASmax} = -23A$, $L=0.5\text{mH}$, $V_{DD} = -48V$, $R_G = 25\Omega$, $V_{GS} = -10V$. Part not recommended for use above this value. 100% Final Test at $I_{AS} = -16A$, $L=0.5\text{mH}$.
 - ⑤ Pulse test; Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
 - ⑥ Guaranteed by design, not subject to production testing.

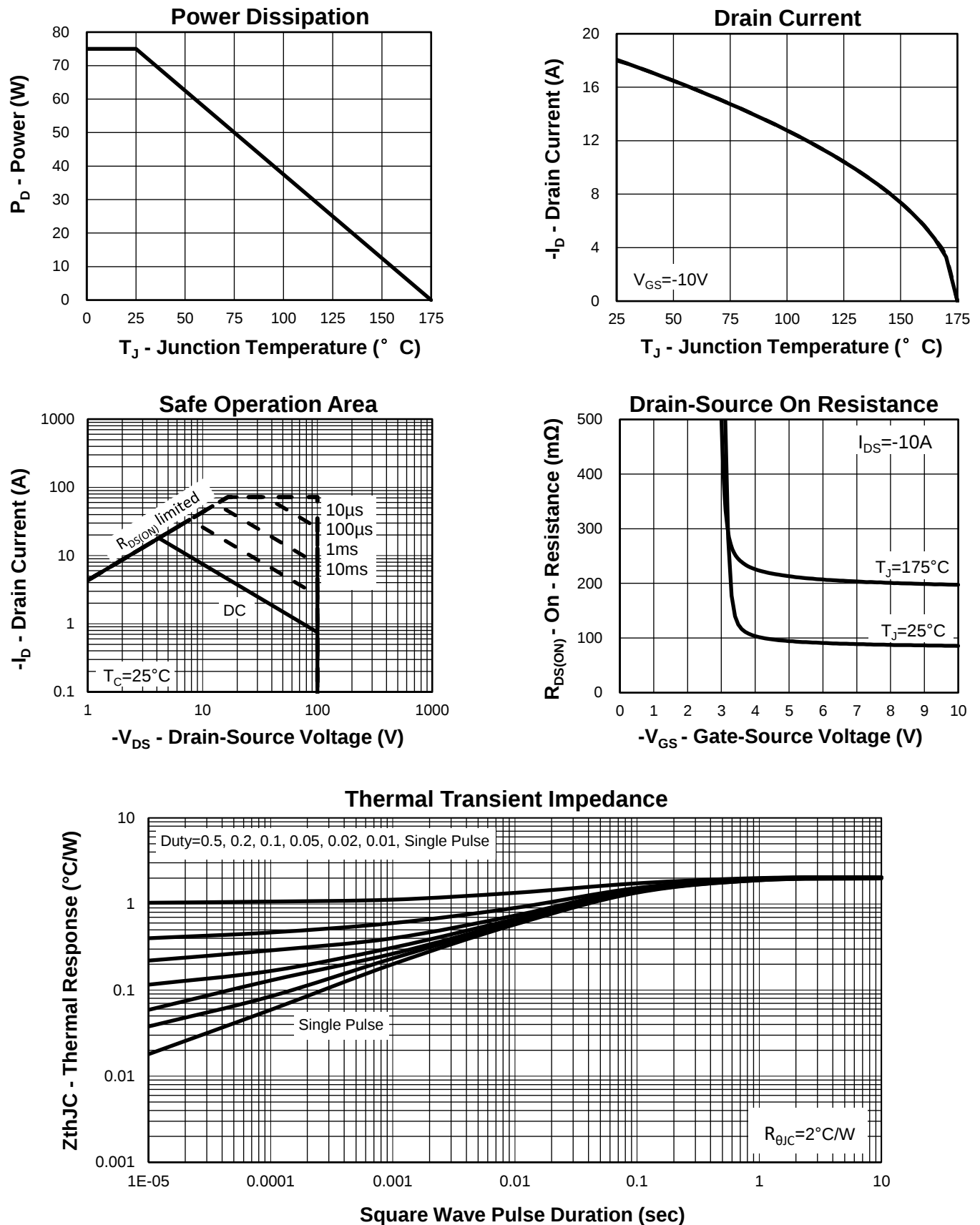
Ordering and Marking Information

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS1308CAT	TO-220	Tube	50	-	-

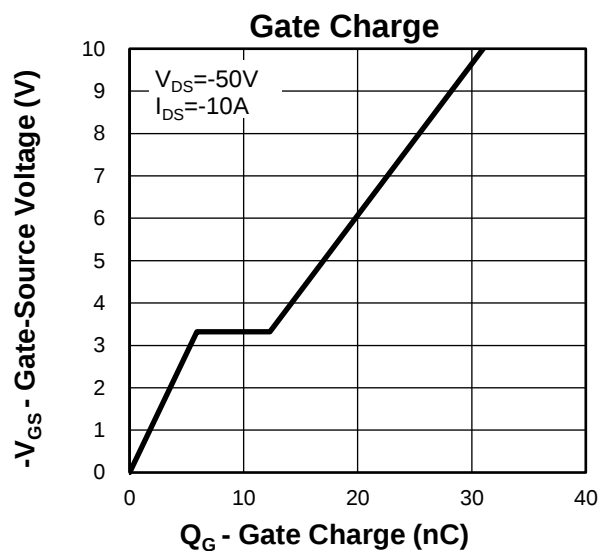
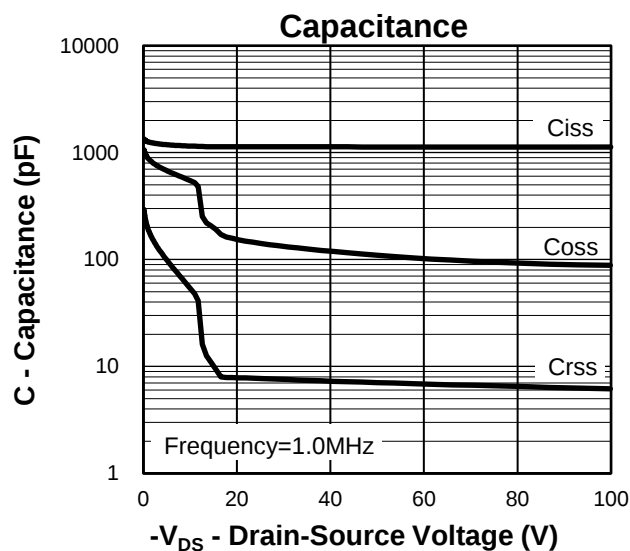
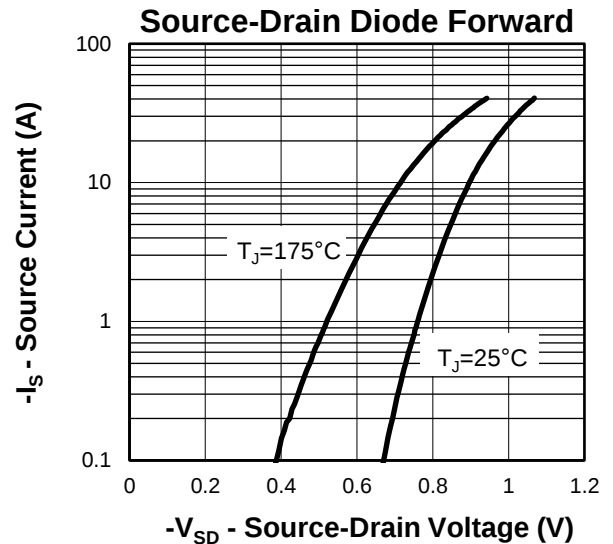
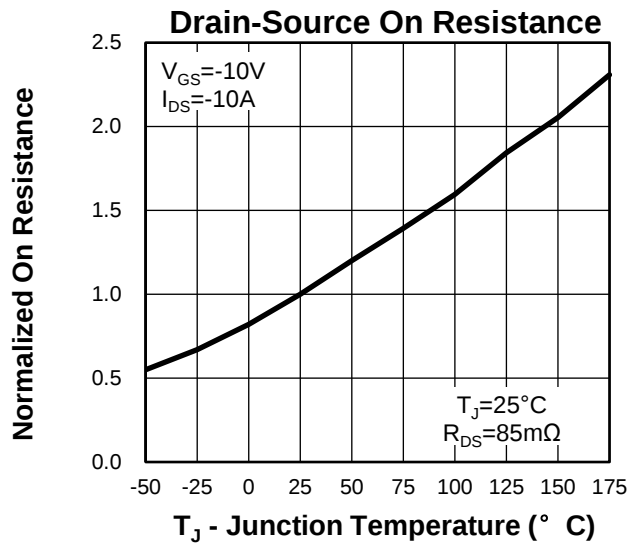
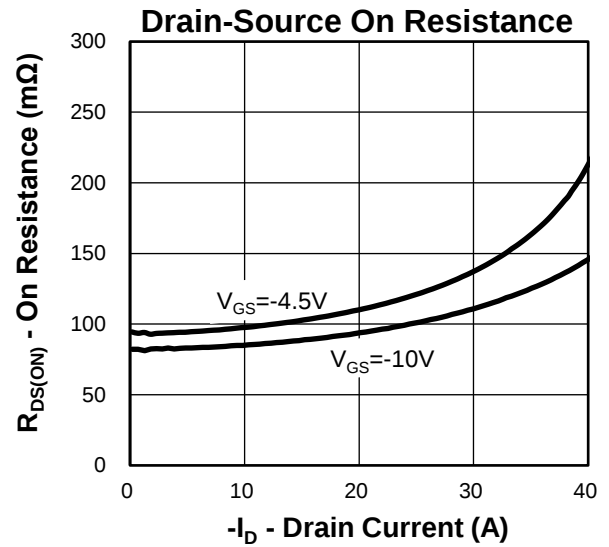
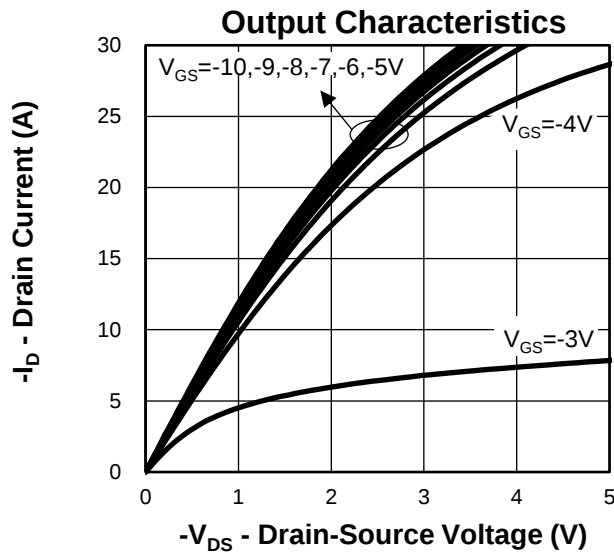


1st Line: Kwansemi LOGO, Kwansemi Code(KS)
2nd Line: Part Number(1308T)
3rd Line: Lot Number(YWWXXX)

Typical Characteristics

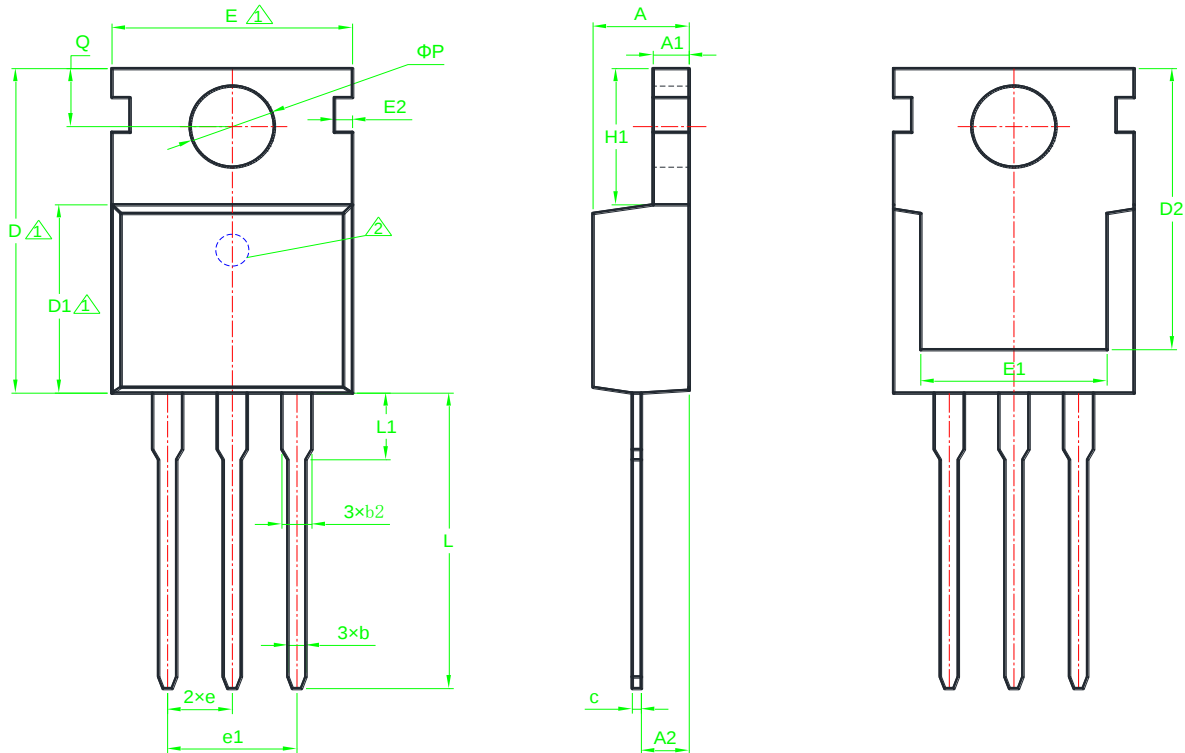


Typical Characteristics



Package Information

TO-220

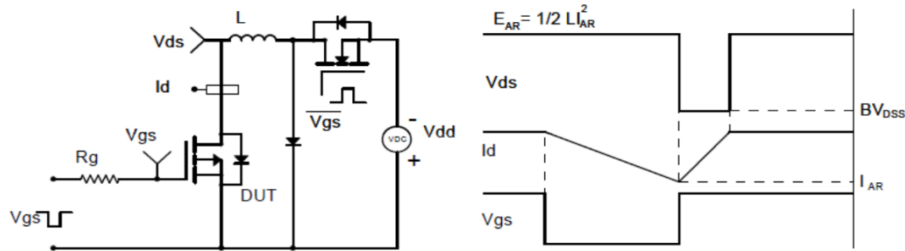


SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.30	4.55	4.80	0.169	0.179	0.189	E1	7.00	*	8.40	0.276	*	0.331
A1	1.20	1.30	1.45	0.047	0.051	0.057	E2	*	*	0.75	*	*	0.030
A2	2.20	2.40	2.70	0.087	0.094	0.106	e	2.54BSC			0.100BSC		
b	0.70	0.80	0.95	0.028	0.031	0.037	e1	5.08BSC			0.200BSC		
b2	1.15	1.35	1.50	0.045	0.053	0.059	H1	6.30	6.50	6.80	0.248	0.256	0.268
c	0.40	0.50	0.60	0.016	0.020	0.024	L	12.70	13.20	13.90	0.500	0.520	0.547
D	15.10	15.60	16.10	0.594	0.614	0.634	L1	2.85	*	3.50	0.112	*	0.138
D1	8.75	9.20	9.65	0.344	0.362	0.380	ØP	3.50	3.65	3.80	0.138	0.144	0.150
D2	12.20	12.50	12.80	0.480	0.492	0.504	Q	2.70	*	2.90	0.106	*	0.114
E	9.70	10.00	10.30	0.382	0.394	0.406							

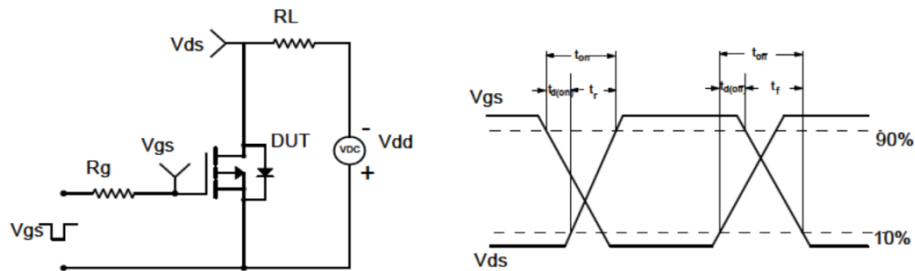
① Dimensions D and D1 and E do not include mold flash protrusions or gate burrs.

② The existence and size of demolding hole are variable depending on mold.

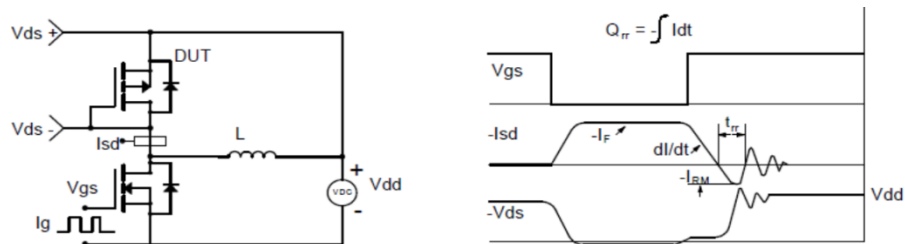
Avalanche Test Circuit and Waveforms



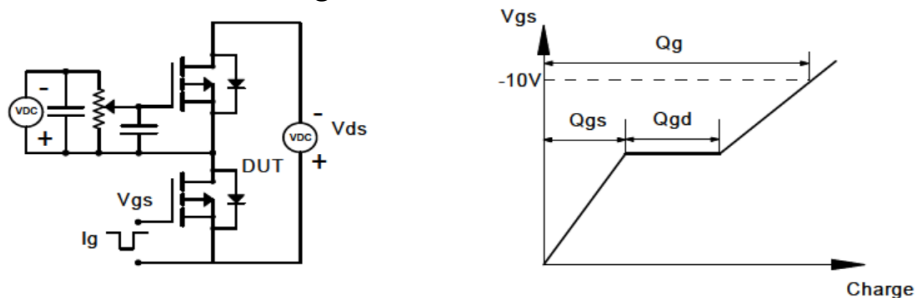
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

Kwansemi Semiconductor Co.,Ltd

Email:Sales@kwansemi.com

Web:www.kwansemi.com

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